

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

Please REWRITE claims 11, 12, 14, and 18-20 as follows:

11. (Once Amended) A method for packaging integrated circuits, comprising:
providing a lead frame of a conductive material with an array [plurality] of lead posts that are equally spaced apart and a connecting sheet connecting each of the [plurality of] lead posts;
attaching a plurality of first dice to the lead frame, wherein each first die is electrically and mechanically connected to a plurality [of the plurality] of lead posts within the array of lead posts, and wherein a conductive side of each first die faces the [plurality of] lead posts; and
encapsulating the plurality of dice with an encapsulating material.
12. (Once Amended) The method, as recited in claim 11, further comprising removing at least part of the connecting sheet to electrically isolate each of the [plurality of] lead posts from each other.
14. (Once Amended) The method, as recited in claim 13, wherein attaching the plurality of first dice to the lead frame comprises placing a conductive epoxy between conductive pads on the plurality of dice and each of the [plurality of] lead posts.
18. (Once Amended) The method, as recited in claim 17, wherein the conductive side of a die of the plurality of dice comprises a plurality of spaced apart conductive pads, wherein the conductive epoxy electrically and mechanically connects each conductive pad to [a] one of the lead posts [of the plurality of posts].
19. (Once Amended) The method, as recited in claim 18, wherein the placing the conductive epoxy comprises:
placing the conductive epoxy on an upper surface of each of the [plurality of] lead posts; and
placing a plurality of dice so that each conductive pad is placed into conductive epoxy on an upper surface of a lead post.

20. (Once Amended) The method, as recited in claim 13, further comprising:
attaching a plurality of second dice to the plurality of first dice, wherein each second die has a conductive side and a side opposite the conductive side, wherein the side opposite the conductive side of each second die is connected to a side opposite the conductive side of a first die, wherein each second die has a plurality of conductive pads on the conductive side of the second die; and
wirebonding conductive pads of each second die to lead posts of the **[plurality] array** of lead posts of the lead frame, wherein encapsulating the plurality of first dice encapsulates the plurality of second dice.

APPENDIX: CURRENTLY PENDING CLAIMS

11. A method for packaging integrated circuits, comprising:
 - providing a lead frame of a conductive material with an array of lead posts that are equally spaced apart and a connecting sheet connecting each of the lead posts;
 - attaching a plurality of first dice to the lead frame, wherein each first die is electrically and mechanically connected to a plurality of lead posts within the array of lead posts, and wherein a conductive side of each first die faces the lead posts; and
 - encapsulating the plurality of dice with an encapsulating material.
12. The method, as recited in claim 11, further comprising removing at least part of the connecting sheet to electrically isolate each of the lead posts from each other.
13. The method, as recited in claim 12, further comprising singulating the encapsulated first dice.
14. The method, as recited in claim 13, wherein attaching the plurality of first dice to the lead frame comprises placing a conductive epoxy between conductive pads on the plurality of dice and each of the lead posts.
15. The method, as recited in claim 14, further comprising testing the integrated circuit packages as a panel before the step of singulation.
16. The method, as recited in claim 15, wherein the removing of the connecting sheet forms lead fingers.
17. The method, as recited in claim 16, wherein the connecting sheet is an imperforate connecting sheet.
18. The method, as recited in claim 17, wherein the conductive side of a die of the plurality of dice comprises a plurality of spaced apart conductive pads, wherein the conductive epoxy electrically and mechanically connects each conductive pad to one of the lead posts.

19. The method, as recited in claim 18, wherein the placing the conductive epoxy comprises:
 - placing the conductive epoxy on an upper surface of each of the lead posts; and
 - placing a plurality of dice so that each conductive pad is placed into conductive epoxy on an upper surface of a lead post.
20. The method, as recited in claim 13, further comprising:
 - attaching a plurality of second dice to the plurality of first dice, wherein each second die has a conductive side and a side opposite the conductive side, wherein the side opposite the conductive side of each second die is connected to a side opposite the conductive side of a first die, wherein each second die has a plurality of conductive pads on the conductive side of the second die; and
 - wirebonding conductive pads of each second die to lead posts of the array of lead posts of the lead frame, wherein encapsulating the plurality of first dice encapsulates the plurality of second dice.
21. A method as recited in claim 11 wherein at least three die are connected to lead posts within the array of lead posts.
22. A method as recited in claim 11 wherein the array of lead posts is at least ten by ten in size.